

Product Change Notification - KSRA-16BWET454

Date: 18 Jul 2017

Product Category: 16-Bit - Microcontrollers and Digital Signal Controllers; Capacitive Touch Sensors; 32-bit PIC Microcontrollers

Notification subject: CCB 3027 Initial Notice: Qualification of CuPdAu bond wire in selected products of the 0.18um TSMC wafer technology available in 44L QFN package at NSEB assembly

Notification text: **PCN Status:**
Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.18um TSMC wafer technology available in 44L QFN package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	NSEB Assembly Site	NSEB Assembly Site
Wire material	Au Wire	CuPdAu Wire
Die attach material	8600	8600
Molding compound material	G700LTD	G700LTD
Lead frame material	C194	C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

January 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

Workweek	July 2017						-->	January 2018				
	26	27	28	29	30	31		01	02	03	04	05
Initial PCN Issue Date				X								
Qual Report Availability								X				
Final PCN Issue Date								X				

Method to Identify Change:
Traceability code

Qualification Plan:
Please open the attachments included with this PCN labeled as PCN_#_Qual Plan

Revision History:
July 18, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

- [PCN_KSRA-16BWET454_Affected CPN.pdf](#)
- [PCN_KSRA-16BWET454_Qual Plan.pdf](#)
- [PCN_KSRA-16BWET454_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_KSRA-16BWET454
CATALOG_PART_NBR
DSPIC33EP128GM304-E/ML
DSPIC33EP128GM304-I/ML
DSPIC33EP128GM604-E/ML
DSPIC33EP128GM604-I/ML
DSPIC33EP128GP504-E/ML
DSPIC33EP128GP504-H/ML
DSPIC33EP128GP504-I/ML
DSPIC33EP128GP504-I/MLA3
DSPIC33EP128GP504T-E/ML
DSPIC33EP128GP504T-I/ML
DSPIC33EP128GS704-E/ML
DSPIC33EP128GS704-I/ML
DSPIC33EP128GS704T-E/ML
DSPIC33EP128GS704T-I/ML
DSPIC33EP128GS804-E/ML
DSPIC33EP128GS804-I/ML
DSPIC33EP128GS804T-E/ML
DSPIC33EP128GS804T-I/ML
DSPIC33EP128MC204-E/ML
DSPIC33EP128MC204-H/ML
DSPIC33EP128MC204-I/ML
DSPIC33EP128MC204-I/MLA3
DSPIC33EP128MC204T-E/ML
DSPIC33EP128MC204T-I/ML
DSPIC33EP128MC504-E/ML
DSPIC33EP128MC504-H/ML
DSPIC33EP128MC504-I/ML
DSPIC33EP128MC504-I/MLA3
DSPIC33EP128MC504T-E/ML
DSPIC33EP128MC504T-H/ML
DSPIC33EP128MC504T-I/ML
DSPIC33EP16GS504-E/ML
DSPIC33EP16GS504-I/ML
DSPIC33EP16GS504T-E/ML
DSPIC33EP16GS504T-I/ML
DSPIC33EP256GM304-E/ML
DSPIC33EP256GM304-I/ML
DSPIC33EP256GM604-E/ML
DSPIC33EP256GM604-I/ML
DSPIC33EP256GP504-E/ML
DSPIC33EP256GP504-H/ML
DSPIC33EP256GP504-I/ML
DSPIC33EP256GP504T-E/ML

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CATALOG_PART_NBR
DSPIC33EP256GP504T-H/ML
DSPIC33EP256GP504T-I/ML
DSPIC33EP256MC204-E/ML
DSPIC33EP256MC204-H/ML
DSPIC33EP256MC204-I/ML
DSPIC33EP256MC204T-E/ML
DSPIC33EP256MC204T-E/MLC02
DSPIC33EP256MC204T-H/ML
DSPIC33EP256MC204T-I/ML
DSPIC33EP256MC504-E/ML
DSPIC33EP256MC504-H/ML
DSPIC33EP256MC504-I/ML
DSPIC33EP256MC504T-E/ML
DSPIC33EP256MC504T-H/ML
DSPIC33EP256MC504T-I/ML
DSPIC33EP32GP504-E/ML
DSPIC33EP32GP504-H/ML
DSPIC33EP32GP504-I/ML
DSPIC33EP32GP504T-E/ML
DSPIC33EP32GP504T-H/ML
DSPIC33EP32GP504T-I/ML
DSPIC33EP32GS504-E/ML
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DSPIC33EP32GS504T-E/ML
DSPIC33EP32GS504T-I/ML
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DSPIC33EP32MC204-H/ML
DSPIC33EP32MC204-I/ML
DSPIC33EP32MC204T-E/ML
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DSPIC33EP32MC204T-I/ML
DSPIC33EP32MC504-E/ML
DSPIC33EP32MC504-H/ML
DSPIC33EP32MC504-I/ML
DSPIC33EP32MC504T-E/ML
DSPIC33EP32MC504T-H/ML
DSPIC33EP32MC504T-I/ML
DSPIC33EP512GM304-E/ML
DSPIC33EP512GM304-I/ML
DSPIC33EP512GM604-E/ML
DSPIC33EP512GM604-I/ML
DSPIC33EP512GP504-E/ML
DSPIC33EP512GP504-H/ML

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DSPIC33EP512GP504T-H/ML
DSPIC33EP512GP504T-I/ML
DSPIC33EP512MC204-E/ML
DSPIC33EP512MC204-H/ML
DSPIC33EP512MC204-I/ML
DSPIC33EP512MC204T-E/ML
DSPIC33EP512MC204T-H/ML
DSPIC33EP512MC204T-I/ML
DSPIC33EP512MC504-E/ML
DSPIC33EP512MC504-H/ML
DSPIC33EP512MC504-I/ML
DSPIC33EP512MC504T-E/ML
DSPIC33EP512MC504T-H/ML
DSPIC33EP512MC504T-I/ML
DSPIC33EP64GP504-E/ML
DSPIC33EP64GP504-H/ML
DSPIC33EP64GP504-I/ML
DSPIC33EP64GP504-I/MLA3
DSPIC33EP64GP504T-E/ML
DSPIC33EP64GP504T-H/ML
DSPIC33EP64GP504T-I/ML
DSPIC33EP64GS504-E/ML
DSPIC33EP64GS504-E/MLC06
DSPIC33EP64GS504-I/ML
DSPIC33EP64GS504T-E/ML
DSPIC33EP64GS504T-I/ML
DSPIC33EP64GS804-E/ML
DSPIC33EP64GS804-I/ML
DSPIC33EP64GS804T-E/ML
DSPIC33EP64GS804T-I/ML
DSPIC33EP64MC204-E/ML
DSPIC33EP64MC204-H/ML
DSPIC33EP64MC204-I/ML
DSPIC33EP64MC204T-E/ML
DSPIC33EP64MC204T-H/ML
DSPIC33EP64MC204T-I/ML
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DSPIC33EP64MC504-I/ML
DSPIC33EP64MC504T-E/ML
DSPIC33EP64MC504T-H/ML
DSPIC33EP64MC504T-I/ML

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DSPIC33EV128GM004-E/ML
DSPIC33EV128GM004-H/ML
DSPIC33EV128GM004-I/ML
DSPIC33EV128GM004T-I/ML
DSPIC33EV128GM104-E/ML
DSPIC33EV128GM104-H/ML
DSPIC33EV128GM104-I/ML
DSPIC33EV128GM104T-I/ML
DSPIC33EV256GM004-E/ML
DSPIC33EV256GM004-H/ML
DSPIC33EV256GM004-I/ML
DSPIC33EV256GM004T-I/ML
DSPIC33EV256GM104-E/ML
DSPIC33EV256GM104-H/ML
DSPIC33EV256GM104-I/ML
DSPIC33EV256GM104T-I/ML
DSPIC33EV32GM004-E/ML
DSPIC33EV32GM004-H/ML
DSPIC33EV32GM004-I/ML
DSPIC33EV32GM004T-I/ML
DSPIC33EV32GM104-E/ML
DSPIC33EV32GM104-H/ML
DSPIC33EV32GM104-I/ML
DSPIC33EV32GM104T-I/ML
DSPIC33EV64GM004-E/ML
DSPIC33EV64GM004-H/ML
DSPIC33EV64GM004-I/ML
DSPIC33EV64GM004T-I/ML
DSPIC33EV64GM104-E/ML
DSPIC33EV64GM104-H/ML
DSPIC33EV64GM104-I/ML
DSPIC33EV64GM104T-I/ML
HA7619-I/ML027
HA7619T-I/ML025
HA7619T-I/ML027
MTCH6301-I/ML
MTCH6301T-I/ML
PIC24EP128GP204-E/ML
PIC24EP128GP204-H/ML
PIC24EP128GP204-I/ML
PIC24EP128GP204-I/MLA3
PIC24EP128GP204T-I/ML
PIC24EP128MC204-E/ML

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PIC24EP128MC204-H/ML
PIC24EP128MC204-I/ML
PIC24EP128MC204-I/MLA3
PIC24EP128MC204T-I/ML
PIC24EP256GP204-E/ML
PIC24EP256GP204-H/ML
PIC24EP256GP204-I/ML
PIC24EP256GP204T-E/ML
PIC24EP256GP204T-H/ML
PIC24EP256GP204T-I/ML
PIC24EP256MC204-E/ML
PIC24EP256MC204-H/ML
PIC24EP256MC204-I/ML
PIC24EP256MC204T-E/ML
PIC24EP256MC204T-H/ML
PIC24EP256MC204T-I/ML
PIC24EP32GP204-E/ML
PIC24EP32GP204-H/ML
PIC24EP32GP204-I/ML
PIC24EP32GP204T-E/ML
PIC24EP32GP204T-H/ML
PIC24EP32GP204T-I/ML
PIC24EP32MC204-E/ML
PIC24EP32MC204-H/ML
PIC24EP32MC204-I/ML
PIC24EP32MC204T-E/ML
PIC24EP32MC204T-H/ML
PIC24EP32MC204T-I/ML
PIC24EP512GP204-E/ML
PIC24EP512GP204-H/ML
PIC24EP512GP204-I/ML
PIC24EP512GP204T-E/ML
PIC24EP512GP204T-H/ML
PIC24EP512GP204T-I/ML
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PIC24EP512MC204T-I/ML
PIC24EP64GP204-E/ML
PIC24EP64GP204-H/ML
PIC24EP64GP204-I/ML

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CATALOG_PART_NBR
PIC24EP64GP204-I/MLA3
PIC24EP64GP204T-E/ML
PIC24EP64GP204T-H/ML
PIC24EP64GP204T-I/ML
PIC24EP64MC204-E/ML
PIC24EP64MC204-H/ML
PIC24EP64MC204-I/ML
PIC24EP64MC204T-E/ML
PIC24EP64MC204T-H/ML
PIC24EP64MC204T-I/ML
PIC24FJ128GA204-E/ML
PIC24FJ128GA204-I/ML
PIC24FJ128GA204T-I/ML
PIC24FJ128GB204-E/ML
PIC24FJ128GB204-I/ML
PIC24FJ128GB204T-I/ML
PIC24FJ64GA204-E/ML
PIC24FJ64GA204-I/ML
PIC24FJ64GA204T-I/ML
PIC24FJ64GB204-E/ML
PIC24FJ64GB204-I/ML
PIC24FJ64GB204T-I/ML
PIC32MX110F016D-I/ML
PIC32MX110F016DT-I/ML
PIC32MX110F016DT-V/ML
PIC32MX110F016D-V/ML
PIC32MX120F032D-50I/ML
PIC32MX120F032D-I/ML
PIC32MX120F032DT-50I/ML
PIC32MX120F032DT-I/ML
PIC32MX120F032DT-V/ML
PIC32MX120F032D-V/ML
PIC32MX130F064D-I/ML
PIC32MX130F064DT-I/ML
PIC32MX130F064DT-V/ML
PIC32MX130F064D-V/ML
PIC32MX130F256D-50I/ML
PIC32MX130F256D-I/ML
PIC32MX130F256DT-50I/ML
PIC32MX130F256DT-I/ML
PIC32MX130F256DT-V/ML
PIC32MX130F256D-V/ML
PIC32MX150F128D-50I/ML

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PCN_KSRA-16BWET454
CATALOG_PART_NBR
PIC32MX150F128D-I/ML
PIC32MX150F128DT-50I/ML
PIC32MX150F128DT-I/ML
PIC32MX150F128DT-V/ML
PIC32MX150F128D-V/ML
PIC32MX170F256D-50I/ML
PIC32MX170F256D-I/ML
PIC32MX170F256DT-50I/ML
PIC32MX170F256DT-I/ML
PIC32MX170F256DT-V/ML
PIC32MX170F256D-V/ML
PIC32MX210F016D-I/ML
PIC32MX210F016DT-I/ML
PIC32MX210F016DT-V/ML
PIC32MX210F016D-V/ML
PIC32MX220F032D-50I/ML
PIC32MX220F032D-I/ML
PIC32MX220F032DT-50I/ML
PIC32MX220F032DT-I/ML
PIC32MX220F032DT-V/ML
PIC32MX220F032D-V/ML
PIC32MX230F064D-I/ML
PIC32MX230F064DT-I/ML
PIC32MX230F064DT-V/ML
PIC32MX230F064D-V/ML
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PIC32MX230F256D-V/ML
PIC32MX250F128D-50I/ML
PIC32MX250F128D-I/ML
PIC32MX250F128DT-50I/ML
PIC32MX250F128DT-I/ML
PIC32MX250F128DT-I/ML026
PIC32MX250F128DT-V/ML
PIC32MX250F128D-V/ML
PIC32MX270F256D-50I/ML
PIC32MX270F256D-I/ML
PIC32MX270F256DT-50I/ML
PIC32MX270F256DT-I/ML
PIC32MX270F256DT-V/ML

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PCN_KSRA-16BWET454
CATALOG_PART_NBR
PIC32MX270F256D-V/ML